



#### 650V FIELD STOP IGBT IN TO247

### Description

The DIODES<sup>™</sup> DGTD65T40S2PT is produced using advanced Field Stop Trench IGBT Technology, which provides excellent quality and high switching performance.

## Applications

- UPS
- Welders
- Solar inverters
- IH cookers

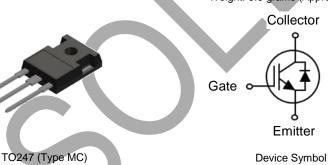
#### Features

- High Speed Switching & Low Power Loss
- VCE(SAT) = 1.8V @ IC = 40A
- t<sub>RR</sub> = 60ns (Typ) @ di<sub>F</sub>/dt = 820A/µs
- E<sub>OFF</sub> = 0.4mJ @ T<sub>C</sub> = +25°C
- Maximum Junction Temperature +175°C
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/104/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please <u>contact us</u> or your local Diodes representative.

https://www.diodes.com/guality/product-definitions/

### **Mechanical Data**

- Package: TO247
- Package Material: Molded Plastic. "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Terminals: Finish Matte Tin Plated Leads. Solderable per MIL-STD-202, Method 208 (3)
- Weight: 5.6 grams (Approximate)



## Ordering Information (Note 4)

С<sub>Е</sub>

| Part Number   | Marking     | Package         | Packing |                           |  |
|---------------|-------------|-----------------|---------|---------------------------|--|
| Fait Number   |             |                 | Qty.    | Carrier                   |  |
| DGTD65T40S2PT | DGTD65T40S2 | TO247 (Type MC) | 450     | Per Box in Tubes (Note 5) |  |

EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

5. 30 Devices per Tube.

### **Marking Information**

Notes:



);; = Manufacturer's Marking DGTD65T40S2 = Product Type Marking Code YY = Year (ex: 22 = 2022) LLLLL = Lot Code WW = Week (01 to 53)



## Absolute Maximum Ratings (@TA = +25°C, unless otherwise specified.)

| Characteristic  |                                  | Symbol | Value | Unit<br>V |  |
|---|----------------------------------|--------|-------|-----------|--|
| Collector-Emitter Voltage                             |                                  | VCE    | 650   |           |  |
| DC Collector Current Limited by T                     | Tc = +25°C                       | Le.    | 80    | А         |  |
| DC Collector Current, Limited by T <sub>Jmax</sub>    | $T_{C} = +100^{\circ}C$          | IC     | 40    | А         |  |
| Pulsed Collector Current, tp Limited by TJmax         |                                  | ICpuls | 120   | А         |  |
| Diada Farward Current Limited by T                    | $T_{\rm C} = +25^{\circ}{\rm C}$ | 1-     | 40    | А         |  |
| Diode Forward Current Limited by T <sub>Jmax</sub>    | $T_{C} = +100^{\circ}C$          | IF     | 20    | А         |  |
| Diode Pulsed Current, tp Limited by T <sub>Jmax</sub> |                                  | IFpuls | 120   | А         |  |
| Gate-Emitter Voltage                                  |                                  | Vge    | ±20   | V         |  |

## Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

| Characteristic   | Symbol | Value       | Unit     |  |
|--|--------|-------------|----------|--|
| Power Dissipation Linear Derating Factor (Note 6) $\frac{T_{C} = +25^{\circ}C}{T_{C} = +100^{\circ}C}$ | PD     | 230<br>115  | W        |  |
| Thermal Resistance, Junction to Ambient (Note 6)   | Reja   | 40          | °C/W     |  |
| Thermal Resistance, Junction to Case for IBGT (Note 6)   | Rejc   | 0.65        |          |  |
| Thermal Resistance, Junction to Case for Diode (Note 6)  | Rejc   | 1.75        |          |  |
| Operating Temperature  | TJ     | -40 to +175 | <u> </u> |  |
| Storage Temperature Range  | Тѕтс   | -55 to +150 | C        |  |

Note: 6. When mounted on a standard JEDEC 2-layer FR-4 board.



# Electrical Characteristics (@T<sub>J</sub> = +25°C, unless otherwise specified.)

| Parameter                             |                         | Symbol              | Min | Тур  | Мах  | Unit                      | Condition   |  |
|---------------------------------------|-------------------------|---------------------|-----|------|------|---------------------------|---|--|
| STATIC CHARACTERISTICS                |                         |                     |     |      |      |                           |   |  |
| Collector-Emitter Breakdown Voltage   |                         | BVCES               | 650 | _    | _    | V                         | $I_C = 2mA$ , $V_{GE} = 0V$   |  |
| Collector-Emitter Saturation Voltage  | $T_J = +25^{\circ}C$    | VCE(SAT)            | _   | 1.8  | 2.30 | v                         | Ic = 40A, V <sub>GE</sub> = 15V   |  |
| Collector-Enlitter Saturation voltage | T <sub>J</sub> = +175°C |                     | _   | 2.30 | _    |                           |   |  |
| Diode Forward Voltage                 | $T_J = +25^{\circ}C$    | VF                  |     | 1.50 | 1.95 | V                         | VGE = 0V, IF = 20A  |  |
|                                       | T <sub>J</sub> = +175°C | VF                  |     | 1.50 |      |                           | VGE = UV, IF = 20A  |  |
| Gate-Emitter Threshold Voltage        |                         | Vge(th)             | 3.5 | 5.0  | 6.5  | N                         | VCE = VGE, IC = 40mA  |  |
| Zero Gate Voltage Collector Current   |                         | ICES                | _   | —    | 40   | μA                        | $V_{CE} = 650 V, V_{GE} = 0 V$  |  |
| Gate-Emitter Leakage Current          |                         | IGES                | _   | _    | ±100 | nA                        | $V_{GE} = 20V, V_{CE} = 0V$   |  |
| DYNAMIC CHARACTERISTICS               |                         |                     |     |      |      |                           |   |  |
| Total Gate Charge                     |                         | Qg                  | _   | 60   |      |                           | VCE = 520V, IC = 40A,   |  |
| Gate-Emitter Charge                   |                         | Qge                 | _   | 13   |      | nC                        | $V_{GE} = 320V, 10 = 40A,$<br>$V_{GE} = 15V$  |  |
| Gate-Collector Charge                 |                         | Qgc                 | _   | 25   |      |                           | VGE - 15V   |  |
| Input Capacitance                     |                         | Cies                | _   | 1565 | _    |                           | V <sub>CE</sub> = 25V, V <sub>GE</sub> = 0V,<br>f = 1MHz  |  |
| Reverse Transfer Capacitance          |                         | Cres                | —   | 37   | _    | pF                        |   |  |
| Output Capacitance                    |                         | Coes                | _   | 120  | —    |                           |   |  |
| SWITCHING CHARACTERISTICS             |                         |                     |     |      |      |                           | -   |  |
| Turn-on Delay Time                    |                         | td(on)              |     | 6    | -    |                           |   |  |
| Rise Time                             |                         | tR                  | _   | 36   |      | ns                        |   |  |
| Turn-off Delay Time                   |                         | t <sub>D(OFF)</sub> | _   | 55   | _    | 110                       | $V_{GE} = 15V$ , $V_{CC} = 400V$ ,<br>IC = 40A, RG = 10 $\Omega$ ,<br>Inductive Load,                             |  |
| Fall Time                             |                         | t⊧                  | —   | 64   |      |                           |   |  |
| Turn-on Switching Energy              |                         | Eon                 | —   | 0.5  | —    | $- T_{VJ} = +25^{\circ}C$ |   |  |
| Turn-off Switching Energy             |                         | EOFF                |     | 0.4  | _    | mJ                        |   |  |
| Total Switching Energy                |                         | Ets                 | -   | 0.9  | _    |                           |   |  |
| Reverse Recovery Time                 |                         | t <sub>RR</sub>     | —   | 60   | _    | ns                        | I <sub>F</sub> = 20A,   |  |
| Reverse Recovery Current              |                         | Irr                 | 1   | 18   |      | А                         | diғ/dt = 820A/µs,   |  |
| Reverse Recovery Charge               |                         | Qrr                 | -   | 696  | _    | nC                        | $T_{VJ} = +25^{\circ}C$   |  |
| Turn-on Delay Time                    |                         | td(on)              | —   | 7    | _    |                           |   |  |
| Rise Time                             |                         | tR                  | _   | 41   |      | ns                        | $V_{GE} = 15V, V_{CC} = 400V,$<br>$I_{C} = 40A, R_{G} = 10\Omega,$<br>Inductive Load,<br>$T_{VJ} = +175^{\circ}C$ |  |
| Turn-off Delay Time                   |                         | tD(OFF)             | _   | 60   | _    | 115                       |   |  |
| Fall Time                             |                         | t⊧                  |     | 102  |      |                           |   |  |
| Turn-on Switching Energy              |                         | Eon                 | _   | 1.04 |      |                           |   |  |
| Turn-off Switching Energy             |                         | EOFF                | _   | 0.57 | _    | mJ                        | 103 - 1175 0  |  |
| Total Switching Energy                |                         | Ets                 | _   | 1.61 | _    |                           |   |  |
| Reverse Recovery Time                 |                         | trr                 |     | 72   | _    | ns                        | I <sub>F</sub> = 20A,   |  |
| Reverse Recovery Current              |                         | IRR                 |     | 22   |      | А                         | diғ/dt = 820A/µs,   |  |
| Reverse Recovery Charge               |                         | Q <sub>RR</sub>     |     | 864  |      | nC                        | T <sub>VJ</sub> = +175°C  |  |



## Typical Performance Characteristics (@TA = +25°C, unless otherwise specified.)

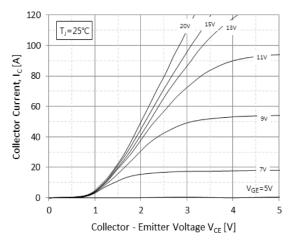
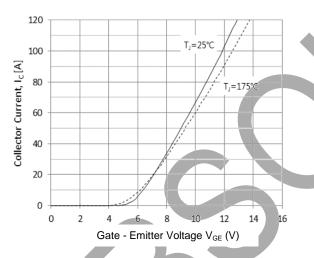
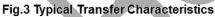


Fig.1 Typical Output Characteristics(T<sub>J</sub>=25℃)





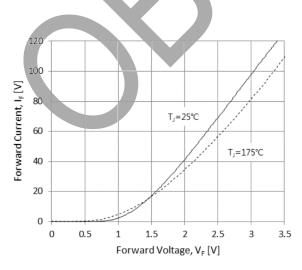


Fig.5 Diode Forward Characteristics

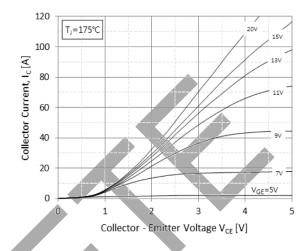


Fig.2 Typical Output Characteristics(TJ=175℃)

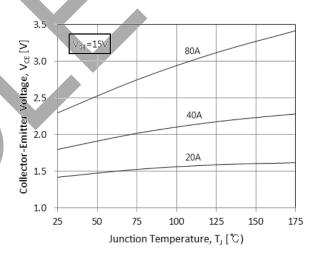


Fig.4 Typical Collector-Emitter Saturation Voltage -Junction Temperature

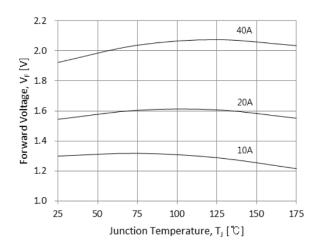
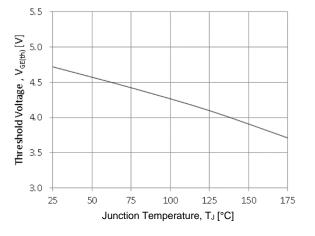


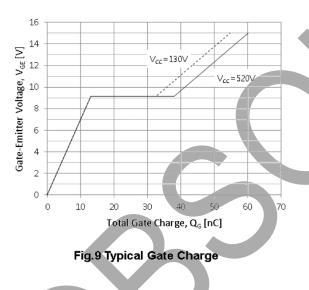
Fig.6 Diode Forward-Junction Temperature



## Typical Performance Characteristics (continued)



### Fig.7 Threshold Voltage-Junction Temperature



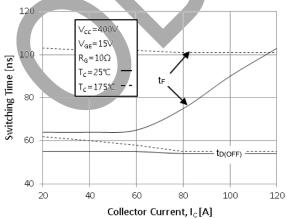
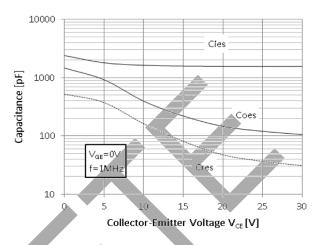
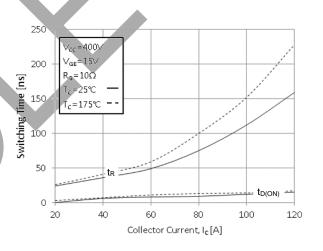


Fig.11 Typical Turn off-Collector Current



### Fig.8 Typical Capacitance



#### Fig.10 Typical Turn on-Collector Current

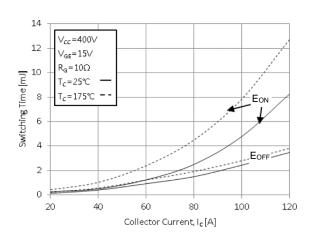
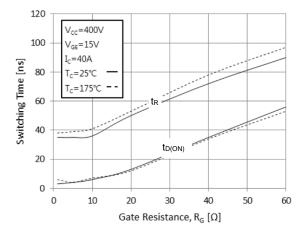


Fig.12 Switching Loss-Collector Current



### Typical Performance Characteristics (continued)



#### Fig.13 Turn on Characteristics-Gate Resistance

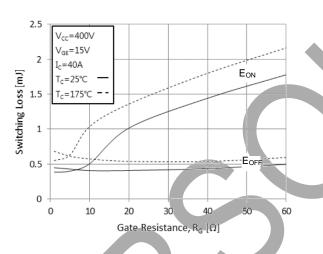
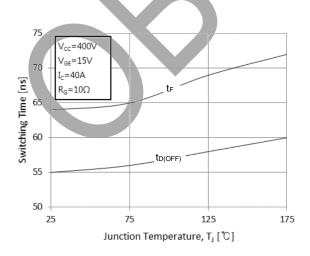
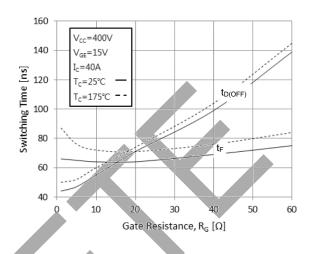


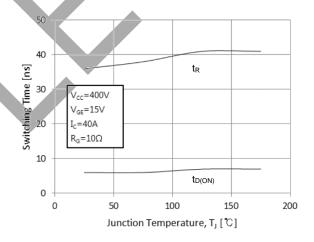
Fig.15 Switching Loss-Gate Resistance







#### Fig.14 Turn off Characteristics-Gate Resistance



#### Fig.16 Turn on Characteristics-Junction Temperature

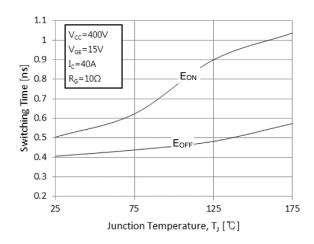
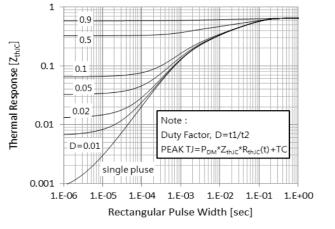


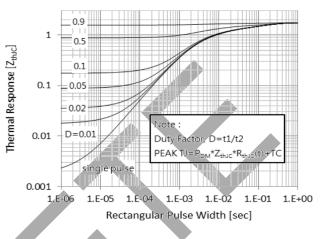
Fig.18 Switching Loss-Junction Temperature



### Typical Performance Characteristics (continued)





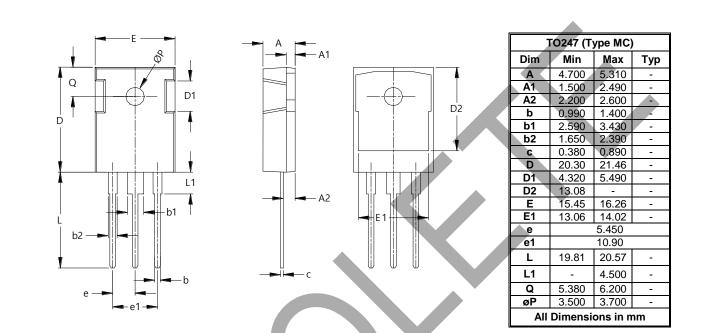


### Fig.20 FRD Transient Thermal Impedance



### **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.



TO247 (Type MC)

Note : For high-voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.



#### IMPORTANT NOTICE

1. DIODES INCORPORATED (Diodes) AND ITS SUBSIDIARIES MAKE NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO ANY INFORMATION CONTAINED IN THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).

2. The Information contained herein is for informational purpose only and is provided only to illustrate the operation of Diodes' products described herein and application examples. Diodes does not assume any liability arising out of the application or use of this document or any product described herein. This document is intended for skilled and technically trained engineering customers and users who design with Diodes' products. Diodes' products may be used to facilitate safety-related applications; however, in all instances customers and users are responsible for (a) selecting the appropriate Diodes products for their applications, (b) evaluating the suitability of Diodes' products for their intended applications, (c) ensuring their applications, which incorporate Diodes' products, comply the applicable legal and regulatory requirements as well as safety and functional-safety related standards, and (d) ensuring they design with appropriate safeguards (including testing, validation, quality control techniques, redundancy, malfunction prevention, and appropriate treatment for aging degradation) to minimize the risks associated with their applications.

3. Diodes assumes no liability for any application-related information, support, assistance or feedback that may be provided by Diodes from time to time. Any customer or user of this document or products described herein will assume all risks and liabilities associated with such use, and will hold Diodes and all companies whose products are represented herein or on Diodes' websites, harmless against all damages and liabilities.

4. Products described herein may be covered by one or more United States, international or foreign patents and pending patent applications. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks and trademark applications. Diodes does not convey any license under any of its intellectual property rights or the rights of any third parties (including third parties whose products and services may be described in this document or on Diodes' website) under this document.

5. Diodes' provided Diodes' Standard Terms and Conditions of Sale products are subject to (https://www.diodes.com/about/company/terms-and-conditions/terms-and-conditions-of-sales/) or other applicable terms. This document does not alter or expand the applicable warranties provided by Diodes. Diodes does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel.

6. Diodes' products and technology may not be used for or incorporated into any products or systems whose manufacture, use or sale is prohibited under any applicable laws and regulations. Should customers or users use Diodes' products in contravention of any applicable laws or regulations, or for any unintended or unauthorized application, customers and users will (a) be solely responsible for any damages, losses or penalties arising in connection therewith or as a result thereof, and (b) indemnify and hold Diodes and its representatives and agents harmless against any and all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim relating to any noncompliance with the applicable laws and regulations, as well as any unintended or unauthorized application.

7. While efforts have been made to ensure the information contained in this document is accurate, complete and current, it may contain technical inaccuracies, omissions and typographical errors. Diodes does not warrant that information contained in this document is error-free and Diodes is under no obligation to update or otherwise correct this information. Notwithstanding the foregoing, Diodes reserves the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. This document is written in English but may be translated into multiple languages for reference. Only the English version of this document is the final and determinative format released by Diodes.

8. Any unauthorized copying, modification, distribution, transmission, display or other use of this document (or any portion hereof) is prohibited. Diodes assumes no responsibility for any losses incurred by the customers or users or any third parties arising from any such unauthorized use.

9. This Notice may be periodically updated with the most recent version available at <a href="https://www.diodes.com/about/company/terms-and-conditions/important-notice">https://www.diodes.com/about/company/terms-and-conditions/important-notice</a>

DIODES is a trademark of Diodes Incorporated in the United States and other countries. The Diodes logo is a registered trademark of Diodes Incorporated in the United States and other countries. © 2022 Diodes Incorporated. All Rights Reserved.

www.diodes.com